

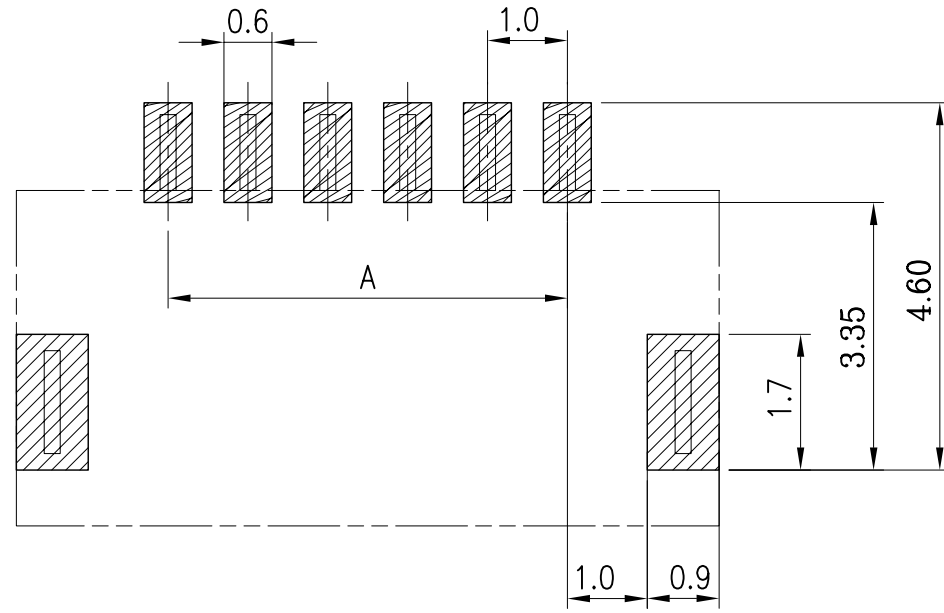


NOTES:

1. MATERIAL:
 - 1.1 HOUSING: HALOGEN FREE PLASTIC, HIGH TEMP., UL94V-0.
 - 1.2 CONTACT: COPPER ALLOY
 - 1.3 FITTING NAIL: COPPER ALLOY
2. FINISH:
 - 2.1 CONTACT: "PER ACES PLATING CODE"
 - 2.2 FITTING NAIL: "PER ACES PLATING CODE"
3. REFLOW SOLDER CAPABLE TO 260° C PER ACES SPEC.
4. SPEC. PLS. REFER TO PS-50264-XXXX-XXX
5. PACKAGE PLS. REFER TO 88330-XXXX-TRP
6. PART NUMBER

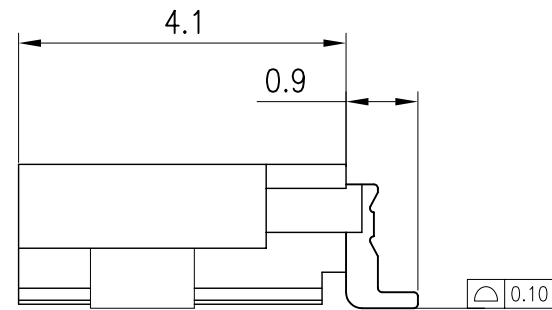
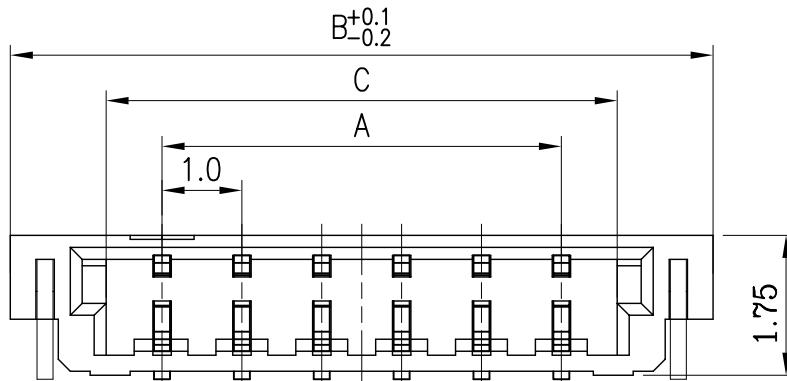
50264-XXX X X-XXX

No. of Ckts: 001
 Packing: 0: Tape&Reel, 1: Tube
 Plating: N: Matt Tin(lead free), 1: G/F over all(lead free)
 Color: Black



P.C. BOARD LAYOUT

CKTS	DIM A	DIM B	DIM C
2	1.00	4.80	2.40
3	2.00	5.80	3.40
4	3.00	6.80	4.40
5	4.00	7.80	5.40
6	5.00	8.80	6.40
7	6.00	9.80	7.40
8	7.00	10.80	8.40
9	8.00	11.80	9.40
10	9.00	12.80	10.40
11	10.00	13.80	11.40
12	11.00	14.80	12.40
13	12.00	15.80	13.40
14	13.00	16.80	14.40
15	14.00	17.80	15.40
16	15.00	18.80	16.40
17	16.00	19.80	17.40
18	17.00	20.80	18.40
19	18.00	21.80	19.40
20	19.00	22.80	20.40
21	20.00	23.80	21.40
22	21.00	24.80	22.40
23	22.00	25.80	23.40
24	23.00	26.80	24.40
25	24.00	27.80	25.40
26	25.00	28.80	26.40
27	26.00	29.80	27.40
28	27.00	30.80	28.40
29	28.00	31.80	29.40
30	29.00	32.80	30.40



一般公差 TOLERANCES X ±0.5 XX ±0.15 X ±0.25 XXX ±0.1 ANGLES ±2°		宏致電子股份有限公司 Aces Electronic Co.,Ltd.	
檢驗尺寸標示 SYMBOLS Ⓞ INDICATE CLASSIFICATION DIMENSION Ⓢ MARK IS CRITICAL DIM. Ⓣ MARK IS MAJOR DIM.		品名 (TITLE) 1.0mm pitch WTB Wafer SMT R/A S/R TYPE 圖號 (DWG.NO) 50264-XXXXX-XXX	
表面處理 (FINISH)		製圖 (DR) liuwe 08/10/13 審核 (CHKD) Sam 核准 (APPD) Jason	
比例 (SCALE) 單位 (UNITS) 10:1 mm		張數 (SHEET) 1 OF 1 尺寸 (SIZE) A4 版次 (REV) 0	

REV	REVISION DESCRIPTION	DATE	SIGNATURE
0	ECN-0810100 NEW DRAWING (APD970355)	08/10/13	liuwei